

IN THE SPECIFICATION

Kindly replace the paragraph in the specification at page 4, lines 1-2 with the following:

Preferred embodiments of the rivet are ~~the subject matter of claims 2 to 5~~ wherein the layer of the less noble metal of the contact piece is 0.1 to 20 μm thick, or preferably wherein the layer of the less noble metal is 0.2 to 2 μm thick. In another preferred embodiment, the less noble metal of the contact piece is Sn, Zn, Mg or Al, and particularly preferably the less noble metal is Sn. A method for the preparation of the contact piece ~~is described in claims 6 to 9.~~ comprises applying a layer of a less noble metal than tungsten (also described herein as a "base metal") onto the contact piece. If there is any less noble metal present on the tungsten overlay, that portion of the less noble metal can be removed. The layer of a less noble metal in a preferred embodiment can be applied via electroplating. In a preferred embodiment, the less noble metal can be applied selectively onto the solder and the metallic support. If there is any less noble metal present on the tungsten overlay after application, that portion of the less noble metal can be removed in a preferred embodiment by sliding grinding.